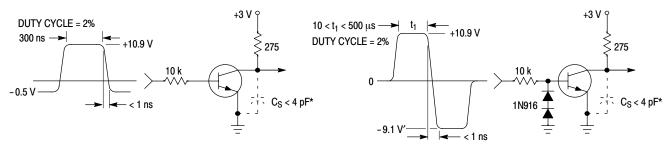
### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Chara	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS			•		
Collector - Emitter Breakdown Voltage (I	V <sub>(BR)CEO</sub>	40	-	Vdc	
Collector - Base Breakdown Voltage (I <sub>C</sub>	V <sub>(BR)CBO</sub>	60	-	Vdc	
Emitter – Base Breakdown Voltage (I <sub>E</sub> =	10 μAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	6.0	-	Vdc
Base Cutoff Current ( $V_{CE}$ = 30 Vdc, $V_{EB}$	= 3.0 Vdc)	I <sub>BL</sub>	-	50	nAdc
Collector Cutoff Current ( $V_{CE}$ = 30 Vdc,	I <sub>CEX</sub>	-	50	nAdc	
ON CHARACTERISTICS (Note 4)					
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $				- - 300 - -	-
$\begin{array}{l} \mbox{Collector}-\mbox{Emitter Saturation Voltage} \\ (I_C = 10 \mbox{ mAdc}, I_B = 1.0 \mbox{ mAdc}) \\ (I_C = 50 \mbox{ mAdc}, I_B = 5.0 \mbox{ mAdc}) \end{array}$	nAdc) - 0.2			Vdc	
$\begin{array}{l} \text{Base - Emitter Saturation Voltage} \\ (I_{C} = 10 \text{ mAdc}, I_{B} = 1.0 \text{ mAdc}) \\ (I_{C} = 50 \text{ mAdc}, I_{B} = 5.0 \text{ mAdc}) \end{array}$	V <sub>BE(sat)</sub>	0.65 -	0.85 0.95	Vdc	
SMALL-SIGNAL CHARACTERISTICS					
Current-Gain - Bandwidth Product (I <sub>C</sub> :	= 10 mAdc, V <sub>CE</sub> = 20 Vdc, f = 100 MHz)	f <sub>T</sub>	300	_	MHz
Output Capacitance (V <sub>CB</sub> = 5.0 Vdc, $I_E$ =	= 0, f = 1.0 MHz)	C <sub>obo</sub>	-	4.0	pF
Input Capacitance (V <sub>EB</sub> = 0.5 Vdc, $I_C$ = 0	0, f = 1.0 MHz)	C <sub>ibo</sub>	-	8.0	pF
Input Impedance (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)		h <sub>ie</sub>	1.0	10	kΩ
Voltage Feedback Ratio (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)		h <sub>re</sub>	0.5	8.0	X 10 <sup>-4</sup>
Small-Signal Current Gain (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)		h <sub>fe</sub>	100	400	-
Output Admittance (V <sub>CE</sub> = 10 Vdc, I <sub>C</sub> = 1.0 mAdc, f = 1.0 kHz)		h <sub>oe</sub>	1.0	40	μmhos
Noise Figure (V <sub>CE</sub> = 5.0 Vdc, I <sub>C</sub> = 100 $\mu$ Adc, R <sub>S</sub> = 1.0 k ohms, f = 1.0 kHz)		NF	-	5.0	dB
SWITCHING CHARACTERISTICS		•	•	•	•
Delay Time	(V <sub>CC</sub> = 3.0 Vdc, V <sub>BE</sub> = -0.5 Vdc.	t <sub>d</sub>	-	35	

Delay Time	(V <sub>CC</sub> = 3.0 Vdc, V <sub>BE</sub> = -0.5 Vdc,	t <sub>d</sub>	-	35	20
Rise Time	$I_{\rm C}$ = 10 mAdc, $I_{\rm B1}$ = 1.0 mAdc)	t <sub>r</sub>	-	35	ns
Storage Time	(V <sub>CC</sub> = 3.0 Vdc,	t <sub>s</sub>	-	200	ns
Fall Time	$I_{C} = 10 \text{ mAdc}, I_{B1} = I_{B2} = 1.0 \text{ mAdc}$	t <sub>f</sub>	-	50	115

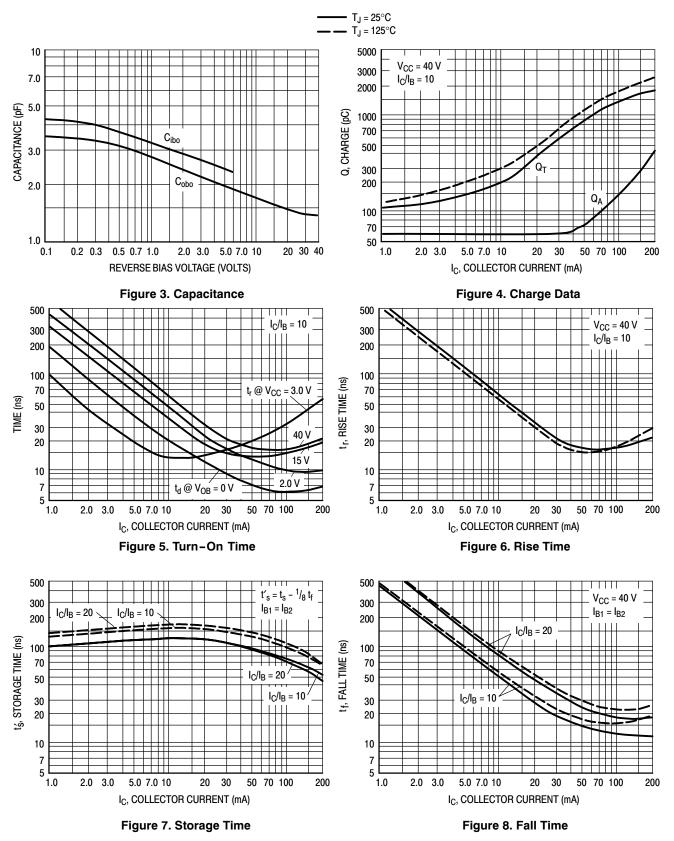
4. Pulse Test: Pulse Width  $\leq$  300 µs, Duty Cycle  $\leq$  2.0%.



\* Total shunt capacitance of test jig and connectors

Figure 1. Delay and Rise Time Equivalent Test Circuit Figure 2. Storage and Fall Time Equivalent Test Circuit

### **TYPICAL TRANSIENT CHARACTERISTICS**



### TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

(V<sub>CE</sub> = 5.0 Vdc,  $T_A$  = 25°C, Bandwidth = 1.0 Hz)

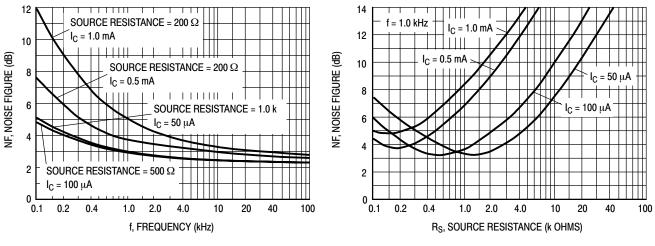
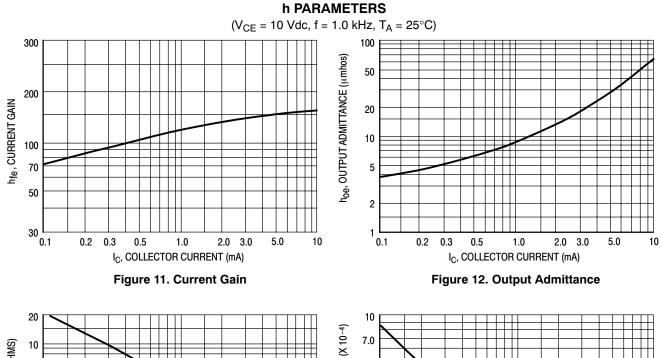
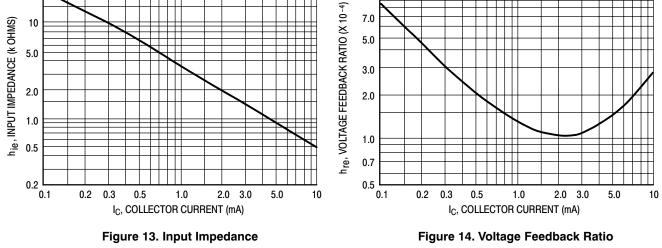


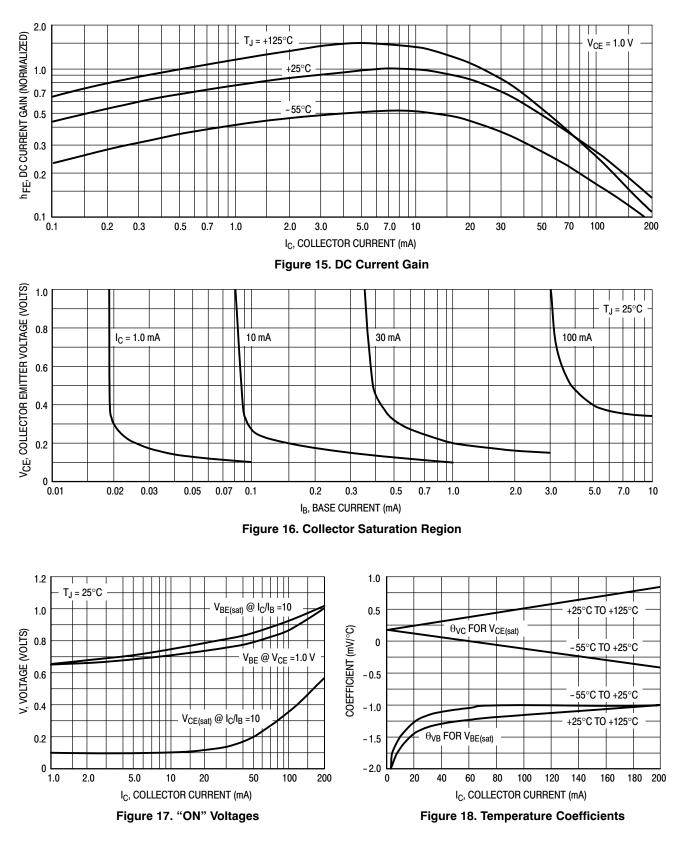
Figure 9.

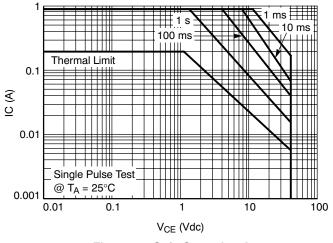


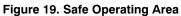




### **TYPICAL STATIC CHARACTERISTICS**

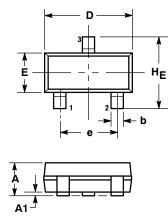


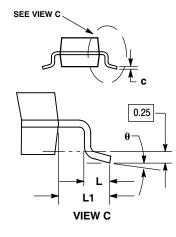




#### PACKAGE DIMENSIONS

#### SOT-23 (TO-236) CASE 318-08 **ISSUE AN**





NOTES:

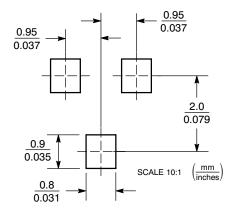
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- 2
- MAXIMUM LEAD THICKNESS INCLUDES LEAD з. FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
- BASE MATERIAL. 318-01 THRU -07 AND -09 OBSOLETE, NEW 4 STANDARD 318-08

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.89	1.00	1.11	0.035	0.040	0.044	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
q	0.37	0.44	0.50	0.015	0.018	0.020	
С	0.09	0.13	0.18	0.003	0.005	0.007	
D	2.80	2.90	3.04	0.110	0.114	0.120	
Ш	1.20	1.30	1.40	0.047	0.051	0.055	
e	1.78	1.90	2.04	0.070	0.075	0.081	
Г	0.10	0.20	0.30	0.004	0.008	0.012	
L1	0.35	0.54	0.69	0.014	0.021	0.029	
ΗE	2.10	2.40	2.64	0.083	0.094	0.104	

STYLE 6: PIN 1. BASE

2. 3. EMITTER COLLECTOR

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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